PCN Number:	20240531002.1	PCN Date:	June 04, 2024
Title:	Qualify UTAC as an additional Assembly site for select devices		
Customer Contact:	Change Management team	Dept:	Quality Services
Proposed 1st Ship Date:	September 02, 2024	Sample requests accepted until:	July 04, 2024

***Sample requests received after** July 04, 2024 **will not be supported.**

Change Type:

☒	Assembly Site	☐	Design	☐	Wafer Bump Material
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process
☒	Assembly Materials	☐	Part number change	☐	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Material
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of UTAC as an additional Assembly site for the list of devices shown below. Material differences as follows between sites.

Assembly Site	Assembly Site Origin	Assembly Country Code	Assembly City
TI Clark Philippines	QAB	PHL	Angeles City, Pampanga
UTAC Thai Limited	NSE	THA	Bangkok

Material Differences:

	TI CLARK	UTAC
Mount compound (Controller die)	4207123	PZ0138
Mold compound	4222198	CZ0421

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings:

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Assembly Site

TI Clark Philippines	Assembly Site Origin (22L)	ASO: QAB
UTAC Thai Limited	Assembly Site Origin (22L)	ASO: NSE

Sample product shipping label (not actual product label)

Product Affected:

SN2102043RVFR	TPS546B24ARVFR	TPS546D24RVFR	TPS546D24ZRVFR
TPS546A24ARVFR	TPS546B24SRVFR	TPS546D24RVFT	
TPS546A24SRVFR	TPS546D24ARVFR	TPS546D24SRVFR	

Qualification Report

Approve Date 09-May-2024

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TPS546D24SRVFR	Qual Device: TPS546B24SRVFR	Qual Device: TPS546A24SRVFR	Qual Device: TPS546D24RVFR	QBS Reference: TPS544C24RVFR
HAST	A2	Biased HAST	110C/85%RH	264 Hours	-	-	-	-	3/231/0
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	1/77/0	-	-	-	3/231/0
TC	A4	Temperature Cycle	-55C/125C	700 Cycles	1/77/0	1/77/0	-	-	3/231/0
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	-	-	3/231/0
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	-	-	-	-	3/66/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	Pass	Pass	Pass	-	Pass
FTY	E6	Final Test Yield	-	-	Pass	Pass	Pass	Pass	Pass

QBS: Qual By Similarity
Qual Device TPS546D24SRVFR is qualified at MSL2 260C
Qual Device TPS546B24SRVFR is qualified at MSL2 260C
Qual Device TPS546A24SRVFR is qualified at MSL2 260C
Qual Device TPS546D24RVFR is qualified at MSL2 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

For questions regarding this notice, e-mails can be sent to Change Management team or your local Field Sales Representative.

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